

Supplementary information for:

A sustainable strategy for fabricating porous carbon supported Sn submicron spheres by self-generated Na₂CO₃ as templates for lithium-ion batteries anode

Kun Liu^{a,1}, Jia-ao Wang^{b,1}, Hongfei Zheng^c, Shuhan Guo^a, Xiaofei Wang^a, Jianzong Man^a, Xinyu Wang^a, Juncai Sun^{a,*}

^aInstitute of Materials and Technology, Dalian Maritime University, Dalian 116026, China

^bDepartment of Chemistry and the Oden Institute for Computational Engineering and Sciences, The University of Texas at Austin, Austin, TX, 78712-0165, USA

^cDepartment of Materials, Xiamen University, Xiamen 361005, China

¹ These authors contributed equally to this work.

***Corresponding author:** sunjc@dlmu.edu.cn (J. Sun)

Supplementary Figures

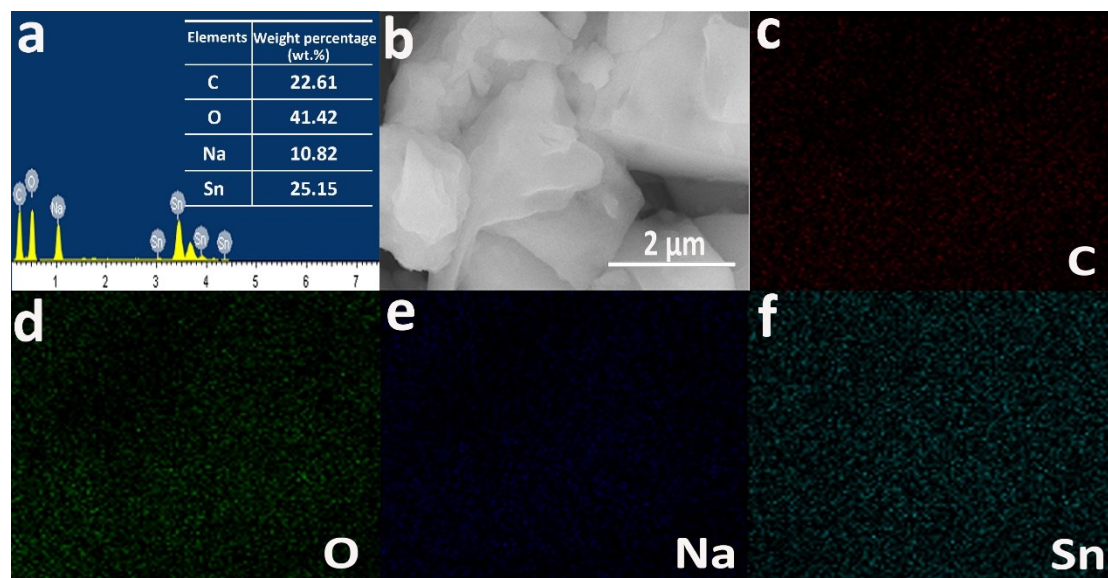


Fig. S1. The basic information of DSSC.

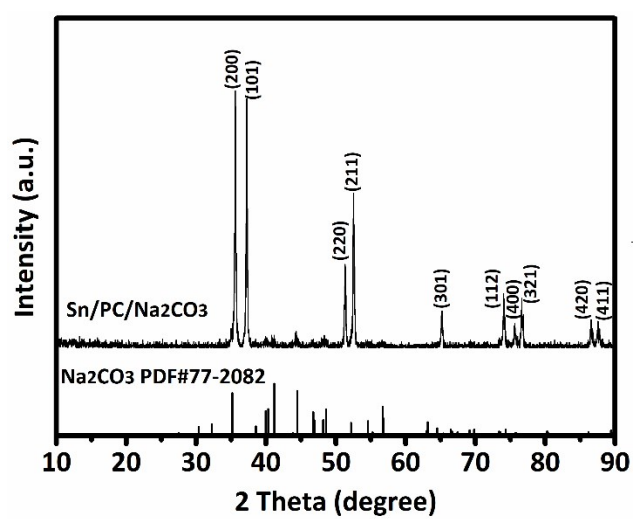


Fig. S2. XRD pattern of unwashed Sn/PC/Na₂CO₃ after carbonization.

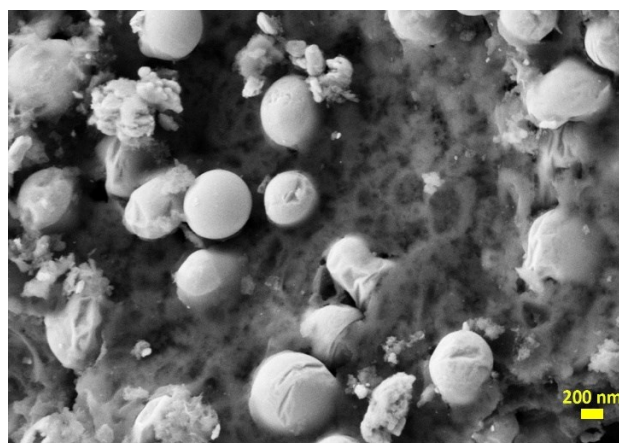


Fig. S3. FE-SEM image of Sn/PC after carbonized at 650 °C.

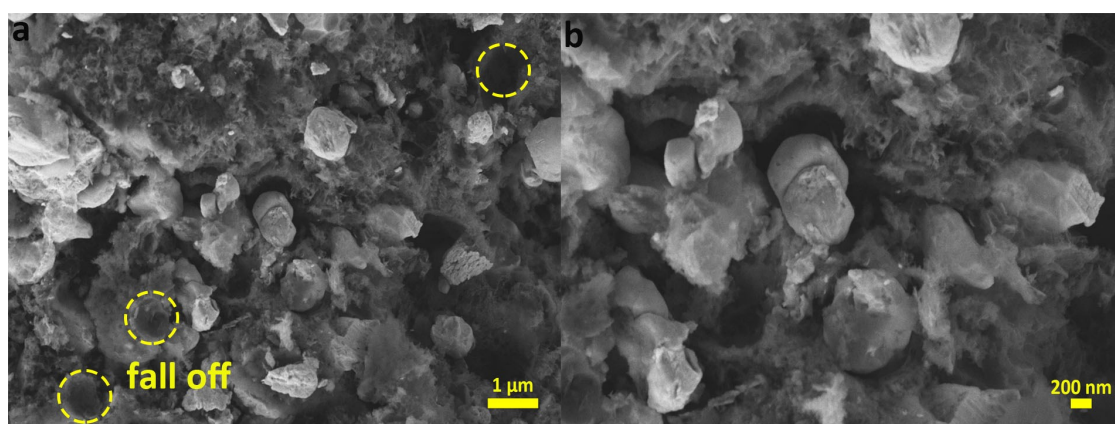


Fig. S4. FE-SEM image of Sn/PC after carbonized at 850 °C.

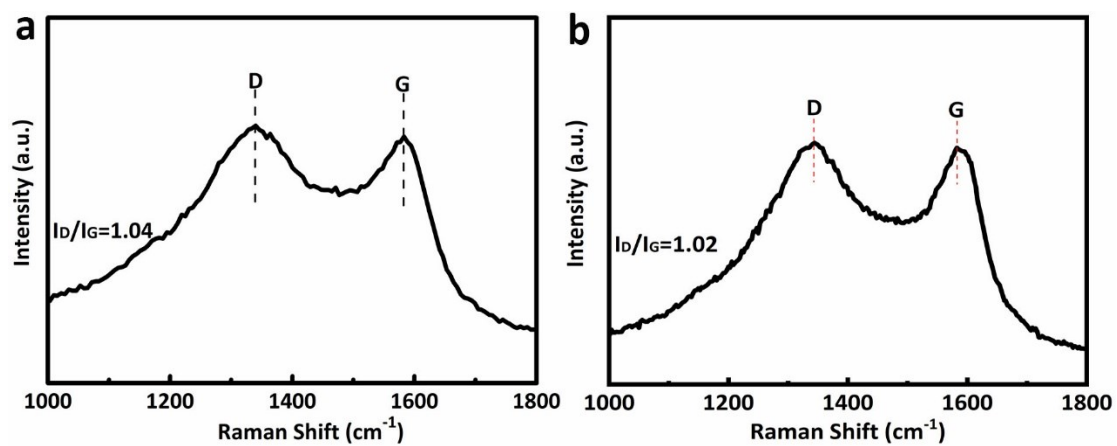


Fig. S5. Raman spectra of (a) Sn/PC and (b) Sn/PC-850.

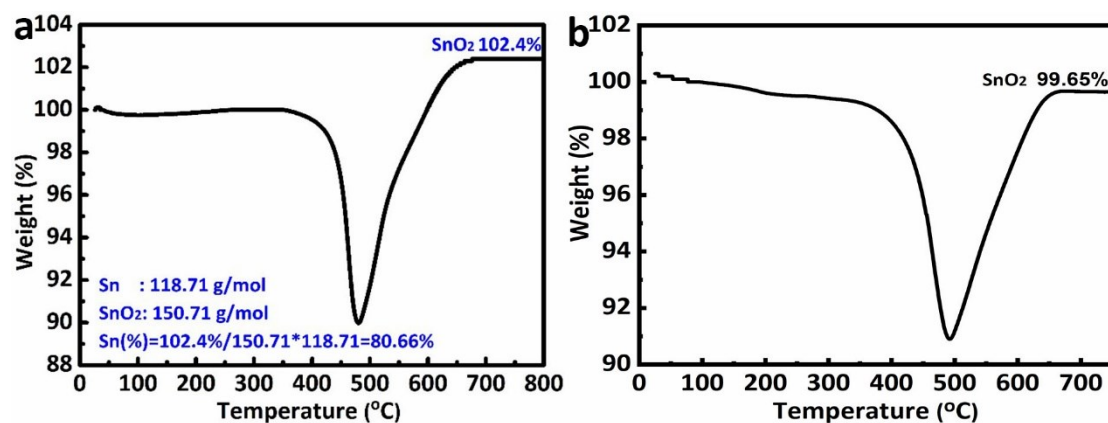


Fig. S6. TGA curves of (a) Sn/PC and (b) Sn/PC-850.

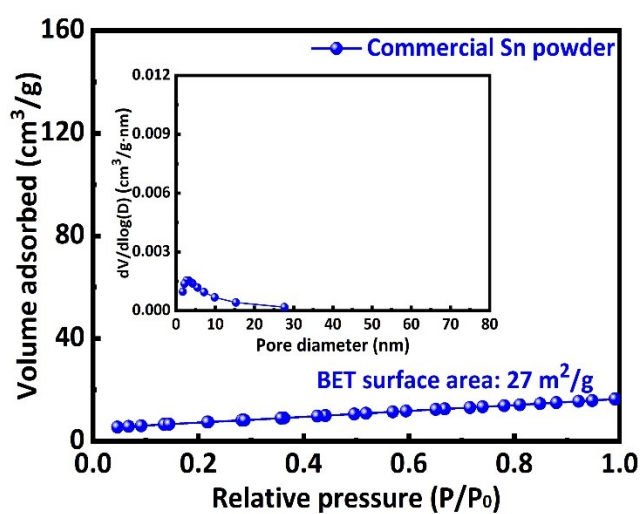


Fig. S7. N₂ adsorption/desorption isotherm of commercial Sn powder (the inset shows pore size distribution curves).

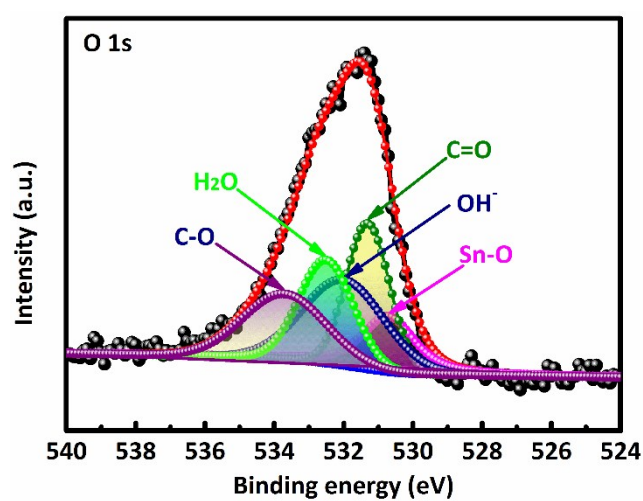


Fig. S8. O 1s spectra of XPS.

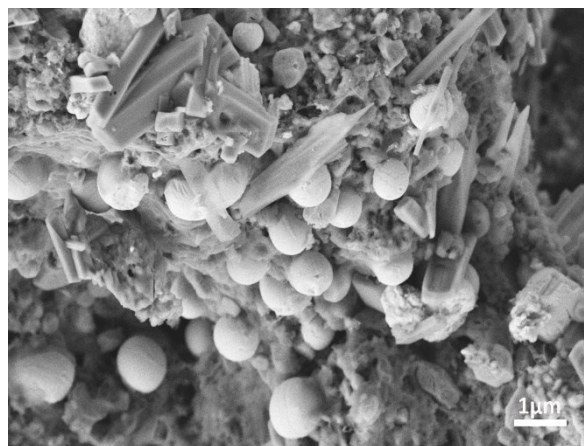


Fig. S9. FE-SEM image of unwashed Sn/PC/Na₂CO₃ after carbonization.

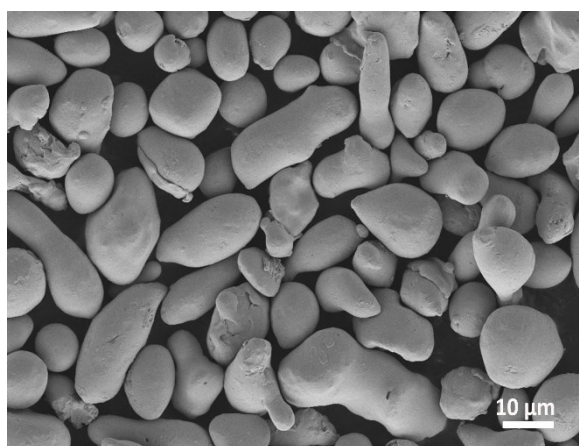


Fig. S10. FE-SEM image of commercial Sn powder.

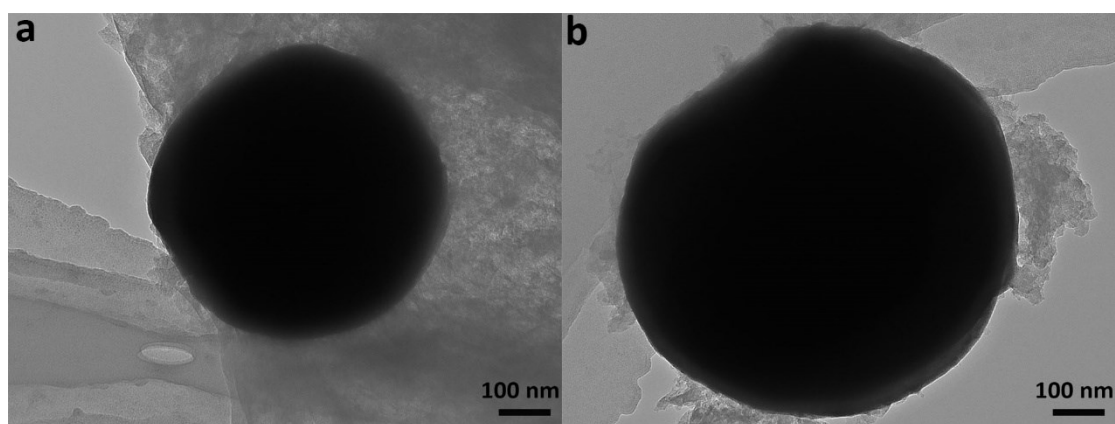


Fig. S11. TEM images of (a) Sn/PC and (b) Sn/PC-850.

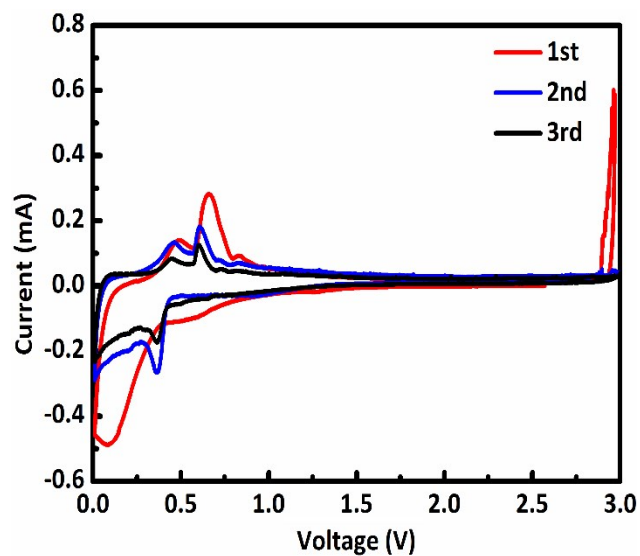


Fig. S12. CV curves of commercial Sn powder.

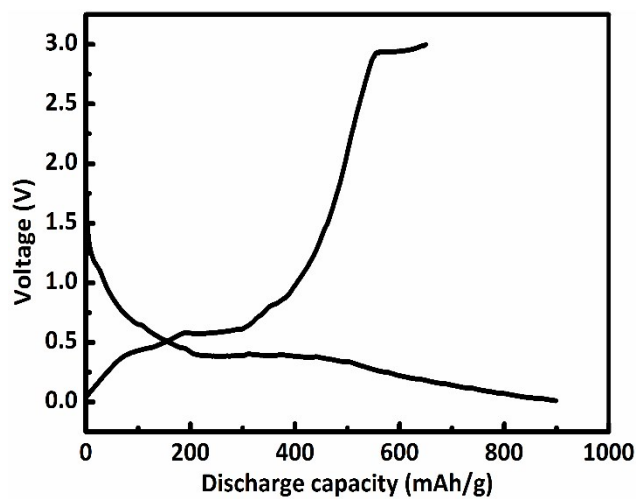


Fig. S13. Initial discharge/charge curve of commercial Sn powder at 100 mA/g.

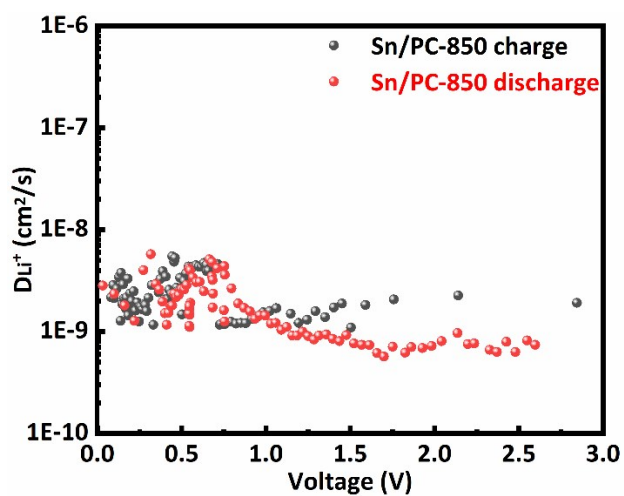


Fig. S14. The Li^+ diffusion coefficient of Sn/PC-850.

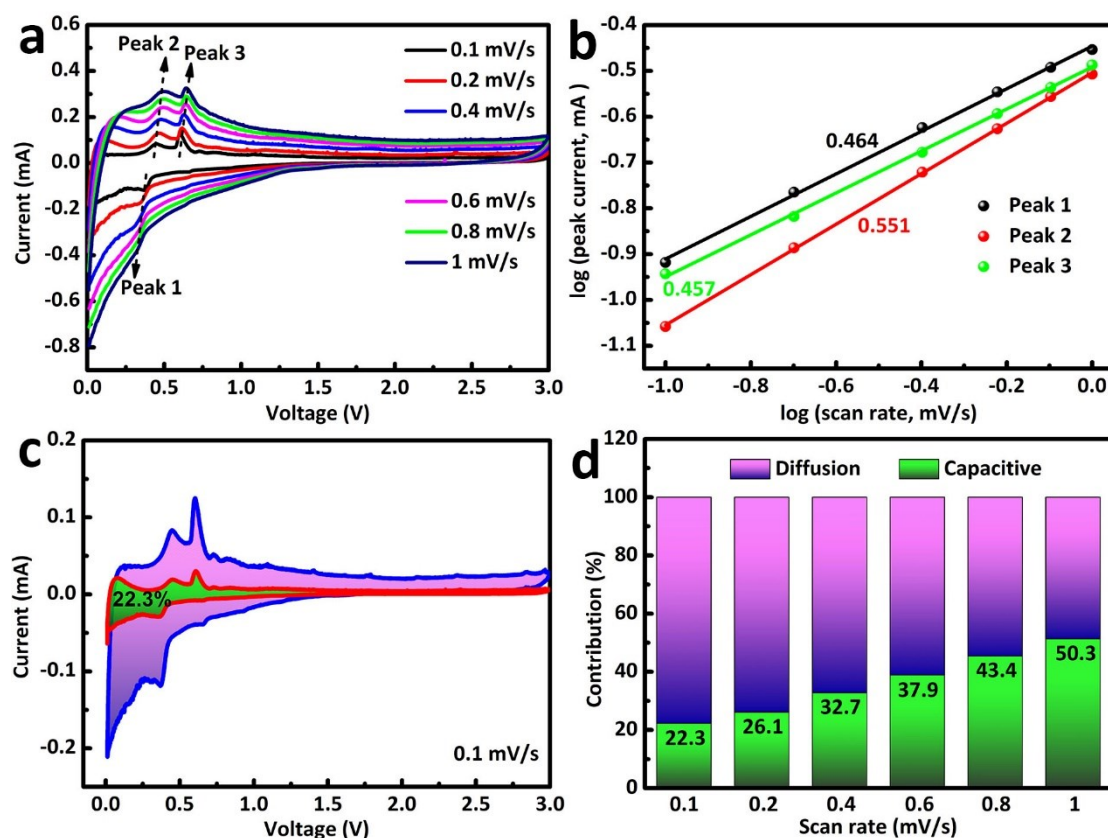


Fig. S15. (a) CV curves of commercial Sn powder at various scan rates from 0.1 to 1 mV/s. (b) The corresponding $\log(i)$ versus $\log(v)$ plots at each redox peak. (c) CV curve at 0.1 mV/s with the capacitive contribution to the total current. (d) The ratio of capacitive and diffusion-controlled contribution at various sweep rates.

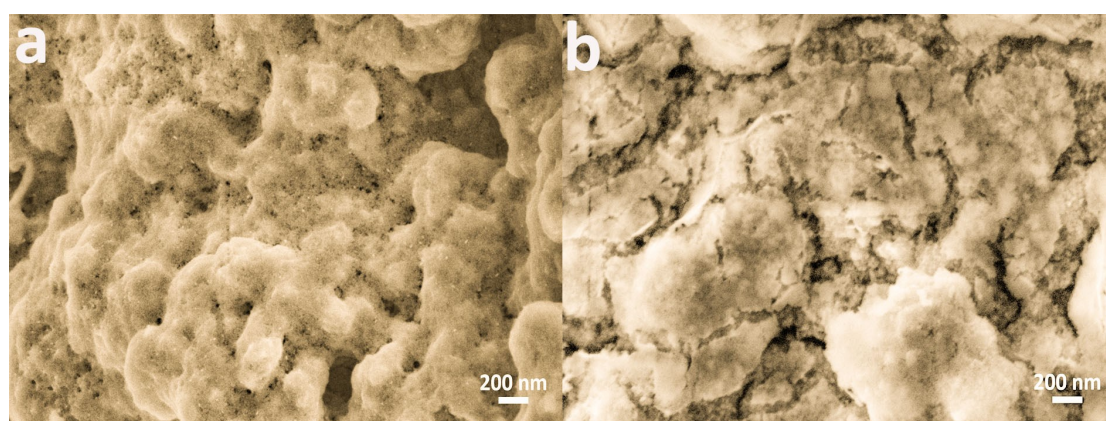


Fig. S16. Morphological characterization after cycling: The SEM images of (a) Sn/PC and (b) commercial Sn powder after 200 cycles at 100 mA/g.

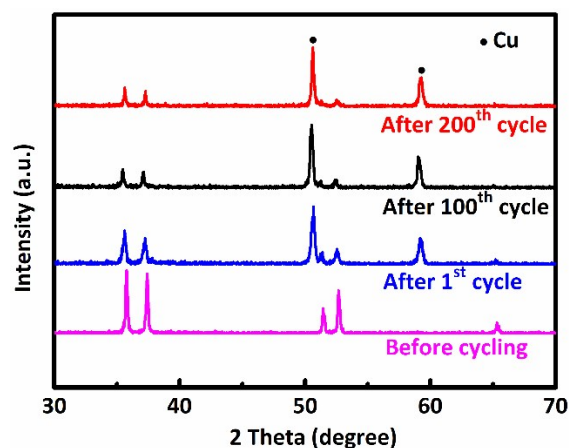


Fig. S17. XRD patterns of Sn/PC after cycling.

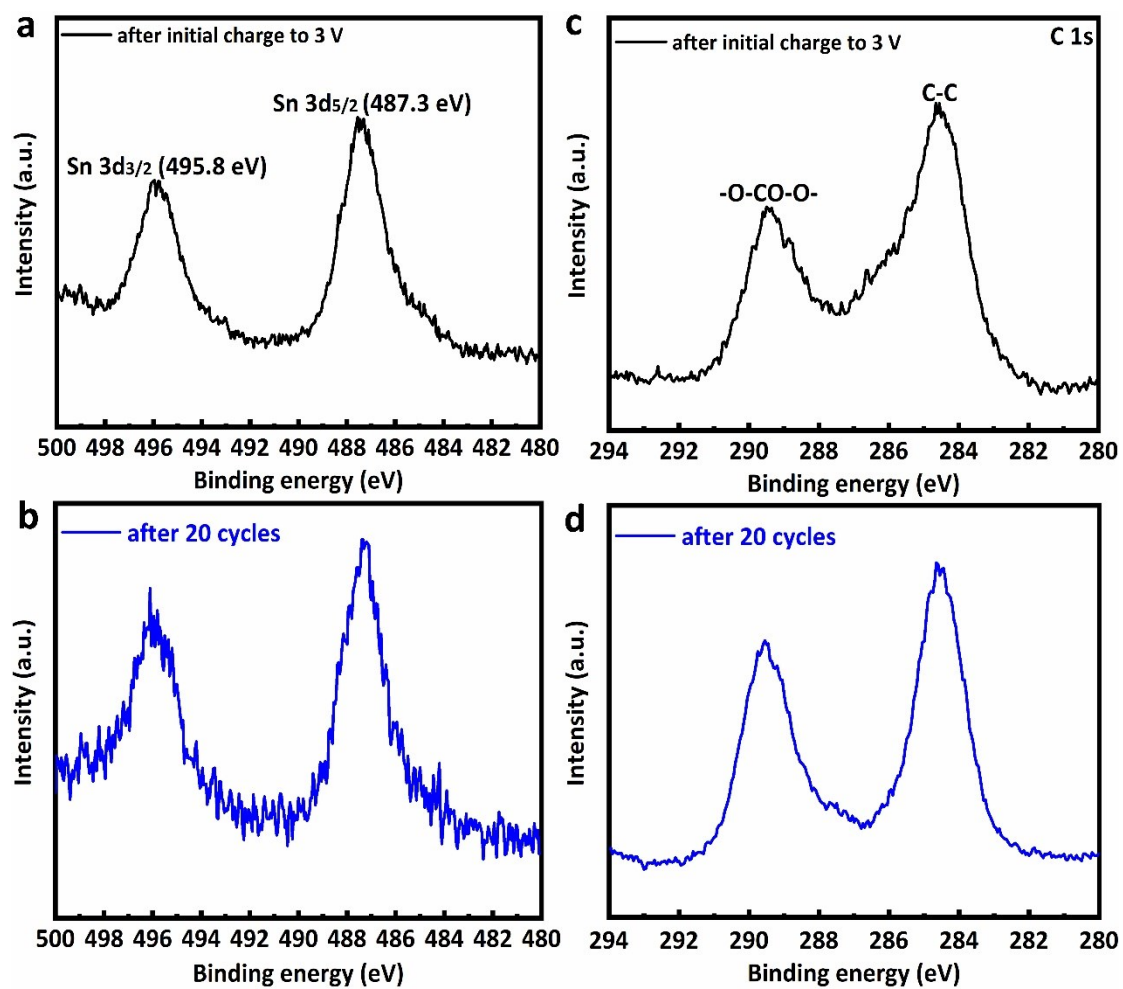


Fig. 18. Ex-situ XPS spectra of Sn/PC electrode after initial charge to 3 V and after 20 cycles: (a-b) Sn 3d; (c-d) C 1s.

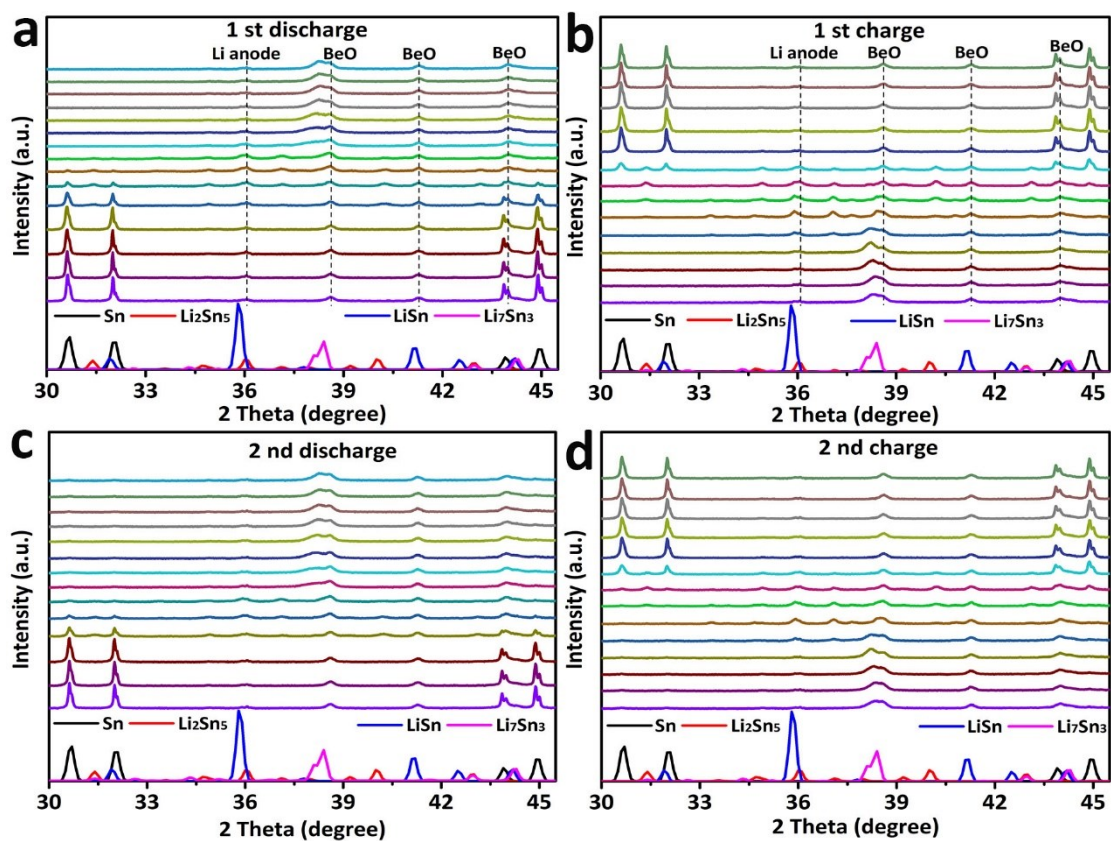


Fig. S19. In-situ XRD patterns of Sn/PC electrode recorded during initial two galvanostatic charge-discharge cycles (100 mA/g).

Table S1. Comparison of the obtained results in this work with previously reported

Materials	Current (mA/g)	Cycle Number	Capacity (mAh/g)	The wastes and hazardous reagents	Ref.
Sn/C core/shell	40	100	546.7	DMF, Tin (II) 2-ethylhexanoate, Anhydrous ethanol, Acetic acid	[1]
C/Sn	100	500	501	Ethanol, Furfural	[2]
Sn/Graphene	100	100	~500	Hydrazine hydrate, Concentrated H ₂ SO ₄ , Concentrated H ₃ PO ₄ , H ₂ O ₂ , KMnO ₄	[3]
Sn/G/GNS	100	200	557	Concentrated H ₂ SO ₄ , Concentrated H ₃ PO ₄ , H ₂ O ₂ , KMnO ₄ , HCl, NaBH ₄	[4]
Sn@C	50	100	520	Absolute ethanol, Formaldehyde, Dimethylformamide (DMF)	[5]
Sn–Ni–Cu	100	50	533	Choline chloride, Ethylene glycol, 1 M HCl	[6]
Sn–Ni@C/G	100	100	503	KCl byproduct, Ethanol	[7]
Sn@2DLMG	100	200	539	Tri(propylene glycol) diacrylate, 1-Hydroxycyclohexyl phenyl ketone	[8]
Sn@Ti3C2Tx	100	200	586.38	Hydrochloric acid, Sodium borohydride	[9]
Porous C/Sn	20	15	~420	NaOH, DMF, Formaldehyde	[10]
Sn–CNF	100	50	~400	DMF, Ethanol	[11]
Sn/PC	100	200	588	Na₂CO₃ template, No hazardous reagents	This work

electrochemical performance of Sn-based composite electrodes for LIBs.

References

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